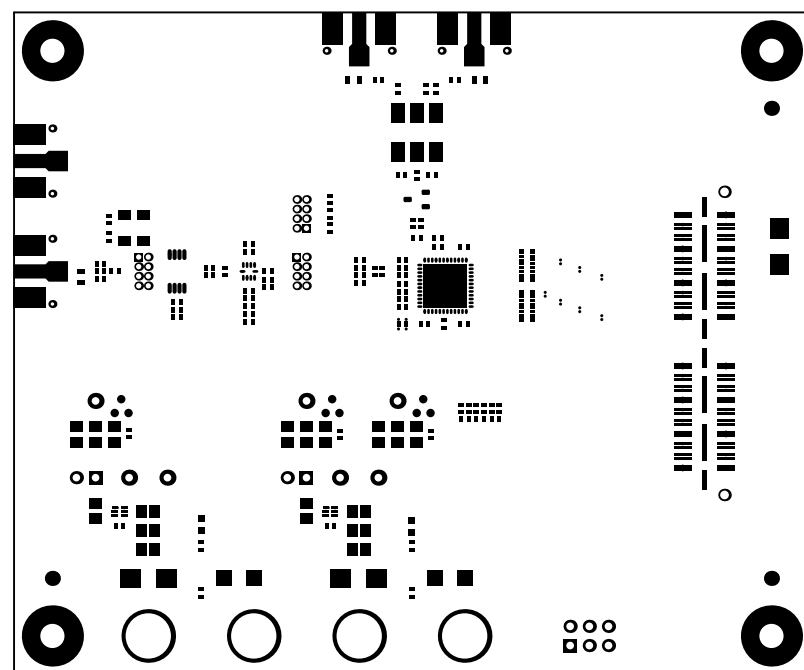
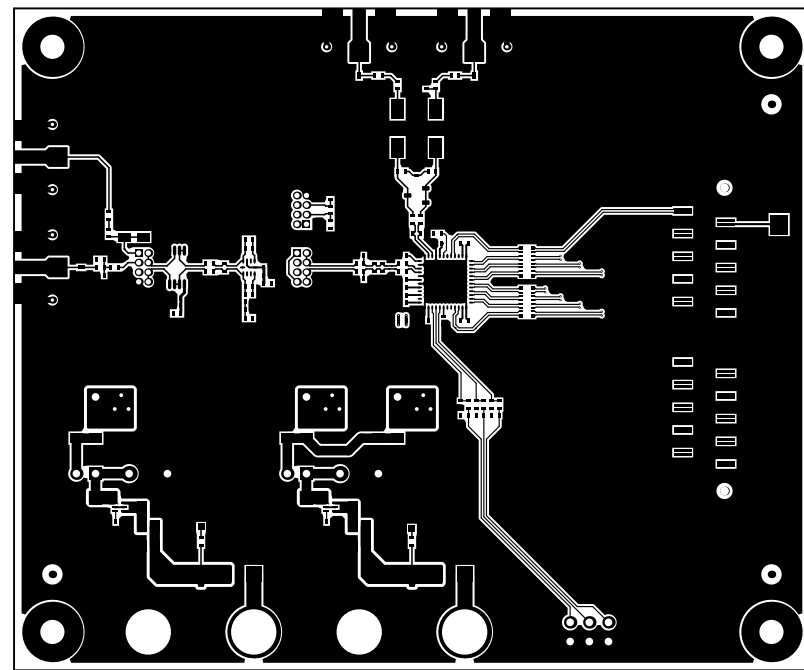


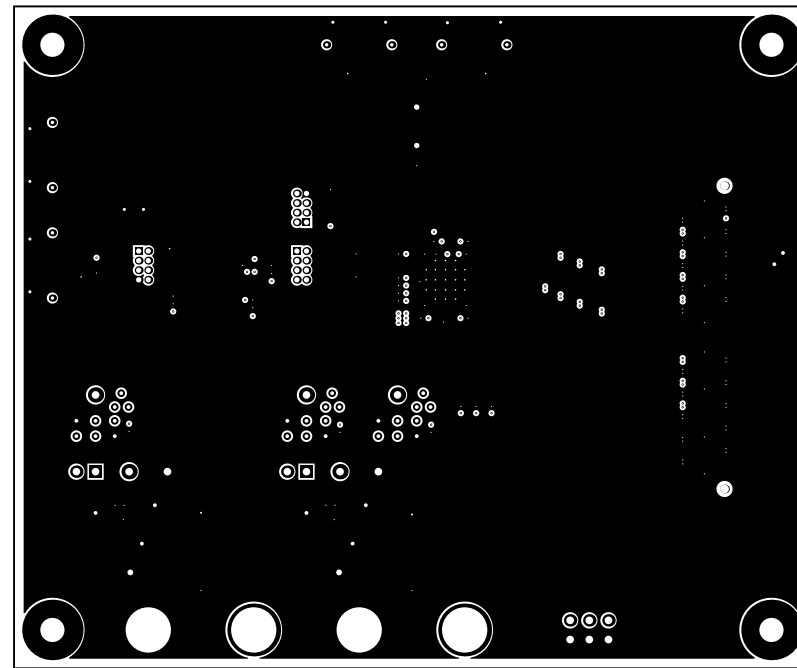
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01403	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 01403		
PLOT NAME = Top Overlay	GENERATED : 7/25/2018 12:20:36 PM	TEXAS INSTRUMENTS	



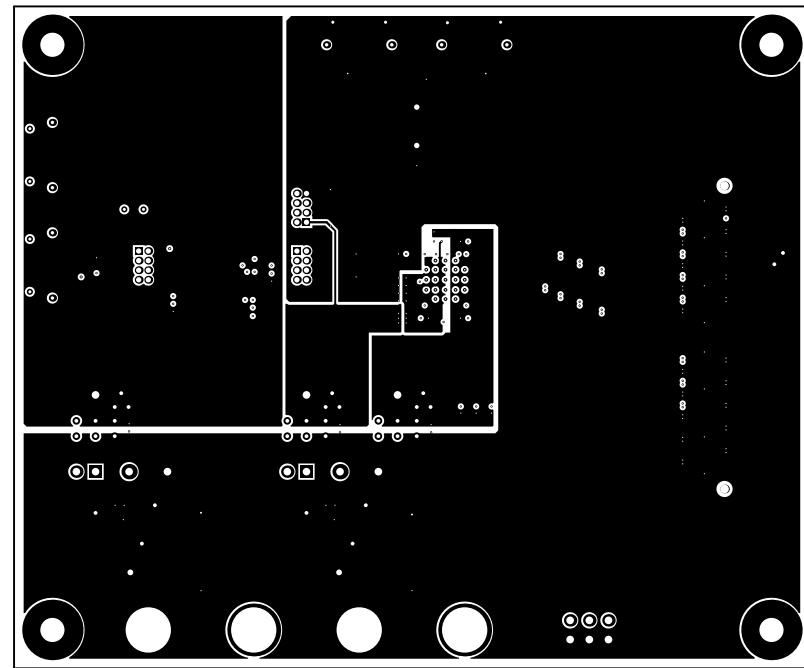
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01403	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 01403		
PLOT NAME = Top Solder Mask	GENERATED : 7/25/2018 12:20:37 PM	TEXAS INSTRUMENTS	



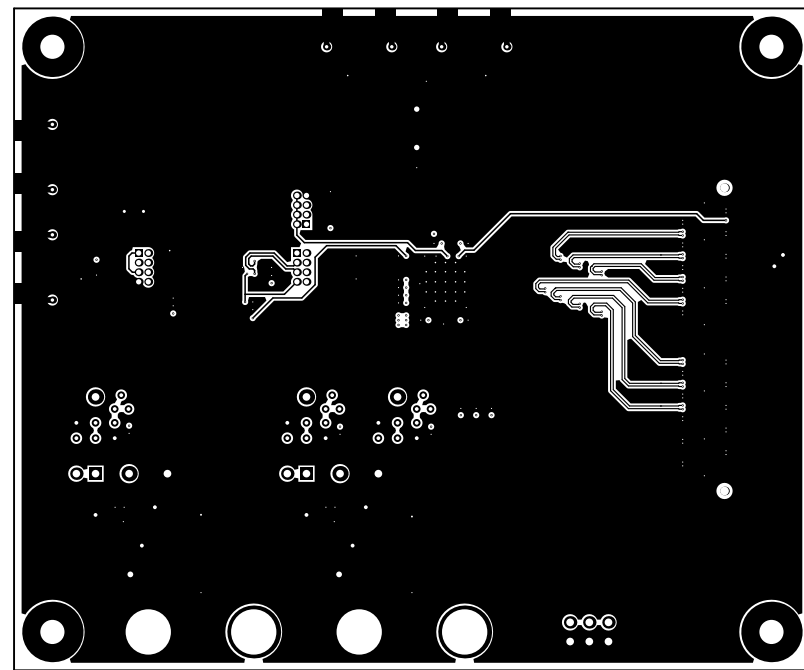
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01403	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: 01403		
PLOT NAME = Top Layer	GENERATED : 7/25/2018 12:20:38 PM	TEXAS INSTRUMENTS	



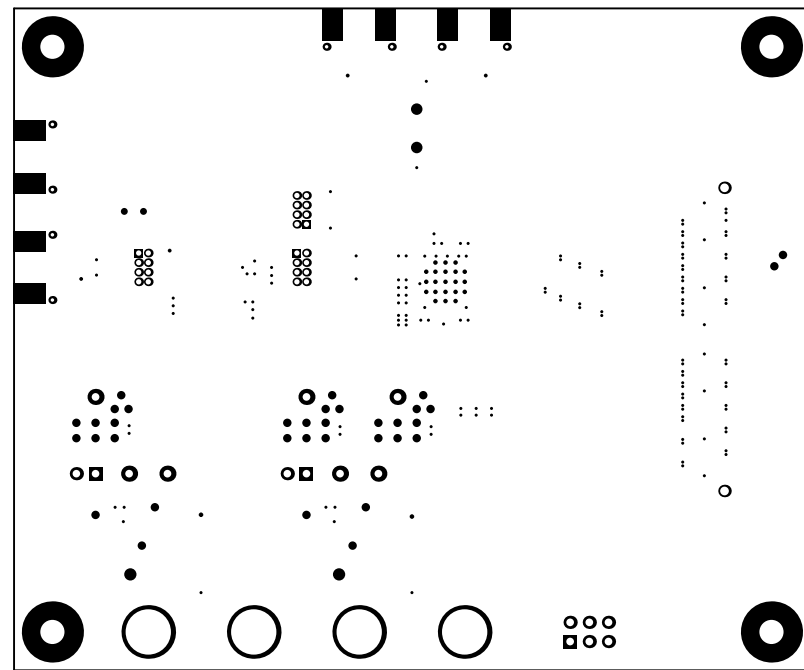
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01403	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = GND	TID #: 01403		
PLOT NAME = Signal Layer 1	GENERATED : 7/25/2018 12:20:39 PM	TEXAS INSTRUMENTS	



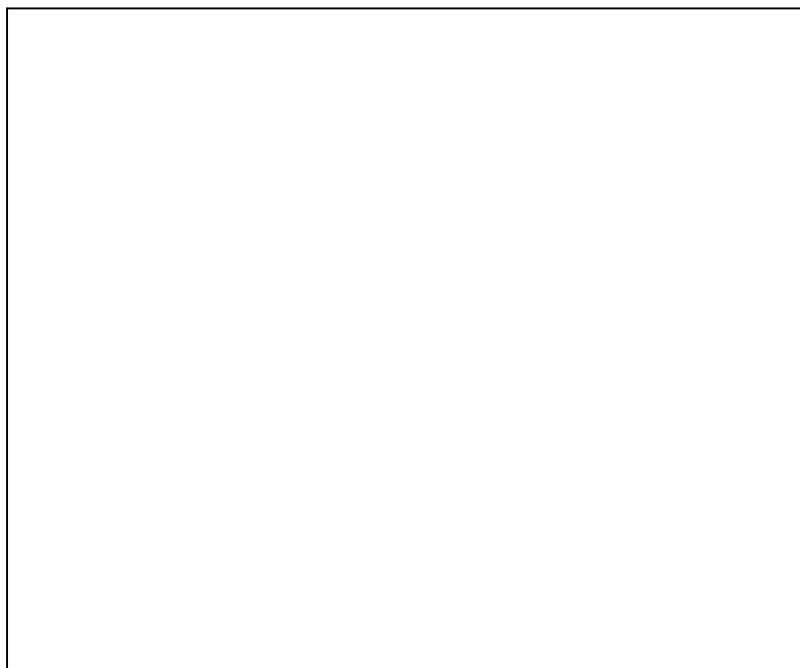
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01403	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = PWR	TID #: 01403		
PLOT NAME = Signal Layer 2	GENERATED : 7/25/2018 12:20:40 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01403	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: 01403		
PLOT NAME = Bottom Layer	GENERATED : 7/25/2018 12:20:41 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01403	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 01403		
PLOT NAME = Bottom Solder Mask	GENERATED : 7/25/2018 12:20:42 PM	TEXAS INSTRUMENTS	



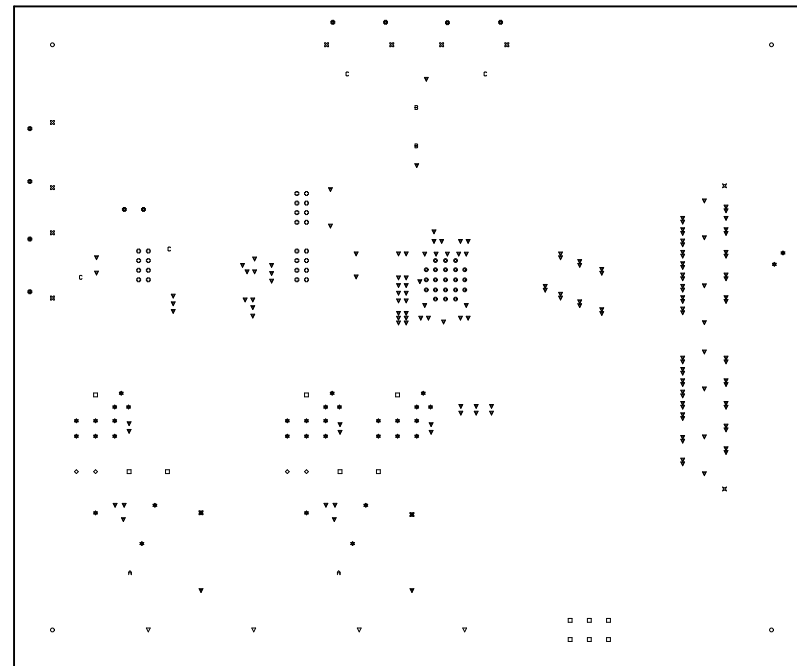
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01403	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: 01403		
PLOT NAME = Bottom Overlay	GENERATED : 7/25/2018 12:20:43 PM	TEXAS INSTRUMENTS	

NOTE: VIAS IN PAD (VP) TO BE FILLED WITH CONDUCTIVE MATERIAL

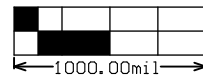
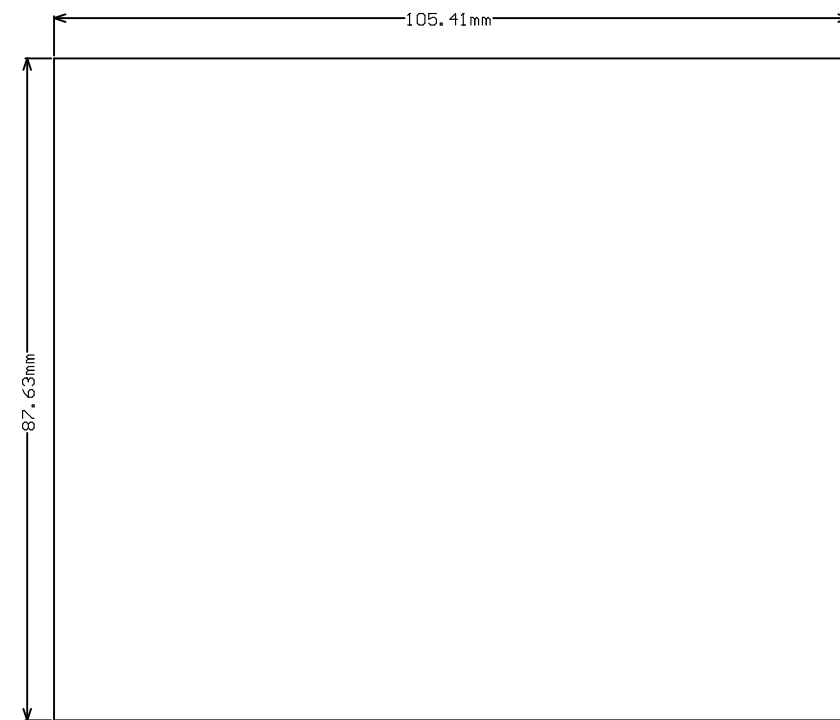
DRILL TABLE

Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
▽	153	6.00mil (0.152mm)	PTH	Round
◎	21	7.87mil (0.200mm)	PTH	Round
C	4	8.00mil (0.203mm)	PTH	Round
⊗	2	10.00mil (0.254mm)	PTH	Round
⊕	10	16.00mil (0.406mm)	PTH	Round
⊗	8	18.00mil (0.457mm)	PTH	Round
⊕	35	20.00mil (0.508mm)	PTH	Round
⊕	24	27.56mil (0.700mm)	PTH	Round
B	2	28.00mil (0.711mm)	PTH	Round
A	2	30.00mil (0.762mm)	PTH	Round
◇	4	39.37mil (1.000mm)	PTH	Round
□	13	40.00mil (1.016mm)	PTH	Round
⊗	2	45.28mil (1.150mm)	NPTH	Round
○	4	125.98mil (3.200mm)	PTH	Round
▽	4	236.22mil (6.000mm)	PTH	Round
	288 Total			

FOR 6MIL DRILL +0/-6MIL
 FOR 7.87MIL DRILL +0/-7.87MIL
 FOR 8MIL DRILL +0/-8MIL
 FOR 10MIL DRILL +0/-10MIL
 FOR 16MIL DRILL +0/-16MIL
 FOR 18MIL DRILL +0/-18MIL
 FOR PTH DRILL +/-3MIL
 FOR NPTH DRILL +/-2MIL



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01403	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 01403		
PLOT NAME = Drill Drawing	GENERATED : 7/25/2018 12:20:44 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01403	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: 01403		
PLOT NAME = Board Dimensions	GENERATED : 7/25/2018 12:20:46 PM	TEXAS INSTRUMENTS	

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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